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**TACK FILM**  
**RTK7556**

**Stress Free**  
**High Thermal Conductivity**  
**Tacky Epoxy Film Adhesive**

**IDEAL FOR:**

- Substrate and Component**
- Die Attach**
- Heat Sink Attach**

**DESCRIPTION:**

RTK7556 is a reworkable, boron nitride-filled, tacky epoxy film adhesive. It is designed for bonding component and substrate to a mismatched substrate or carrier. This B-staged conductive adhesive offers excellent reworkability at 80-150°C.

RTK7556 has high thermal conductivity and the low Tg adhesive imposes minimum thermal stress on bonded parts during thermal cycling or shock testing.

**AVAILABILITY:**

RTK7556 is available in reels, sheets, or as custom preforms. Standard thicknesses are 0.003" and 0.006". Special thicknesses are available. This material is a self-supporting, tacky epoxy film adhesive.

**APPLICATION PROCEDURES:**

- ( 1 ) Keep product at room temperature for at least minutes before using.
- ( 2 ) Cut to desired size.Clean contact surfaces if needed.
- ( 3 ) Remove one side of the release liner by peeling up a corner of the release liner. Fold the release liner over, approaching a 180° angle.  
 Pull the release liner quickly, removing it with one stroke. Apply to substrate, then remove other side of release liner and attach die or component.
- ( 4 ) Cure according to one of the recommended schedule

**TYPICAL PROPERTIES\***

|  |  |
|--|--|
| Electrical Resistivity<br>( 150 °C/ 30 minut ) | >1x10 <sup>14</sup> ohm-cm                     |
| Dielectric Strength (Volts/mil)                | 750  |
| Glass Transition Temp.(°C)                     | -60  |
| Lap-Shear Strength                             | >500 psi<br>>3.4 N/mm <sup>2</sup>             |
| Device Push-off Strength                       | >1000 psi<br>>6.9 N/mm <sup>2</sup>            |
| Hardness (Type)                                | 82 (A)   |
| Cured Density (gm/cc)                          | 1.2  |
| Thermal Conductivity                           | 24 Btu-in/hr-ft <sup>2</sup> -°F<br>3.4 W/m-°C |
| Linear Thermal Expansion<br>Coeff. (ppm/°C)    | 110  |
| Maximum Continuous<br>Operation Temp. (°C)     | 150  |

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

| Temperature | Time   | Pressure |
|-------------|--------|----------|
| 100°C       | 2 hr   | 5-10 psi |
| 125°C       | 1 hr   | 5-10 psi |
| 150°C       | 30 min | 5-10 psi |

The die or component can also be tacked on the substrate at 125°C or higher with 10 psi. When a fillet around the edge of the die or component is observed, the pressure can be released for the rest of the bonding cycle.

**SHELF LIFE:**

| Storage temperature | Shelf Life                |
|---------------------|---------------------------|
| 0-5°C               | 1 yr<br>in sealed package |

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to MSDS for more details.

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